

7334L2622F01LF

Catalogue Part Number Key

Lead Free Version (Optional)

Plating : contact area
 2: 0.4 µm Gold
 5: 2.0 µm Gold

Number of contacts :
 2: 8 contacts ISO
 3: 16 contacts ISO + AFNOR

GENERAL:
 This L26 connector uses a "sliding" contact technology suitable for most applications.
 It has been designed for easy mounting on the PCB.

ELECTRICAL PROPERTIES:
 Insulation resistance : 5000 MΩ min
 Dielectric withstanding : 750 Vrms min
 Current carrying capacity : 10µA min. 1A max
 Contact resistance : 100mΩ max
 Card sensor type : Normally closed

MECHANICAL PROPERTIES:
 Contact Normal force : 0.6 N max (EMV Standard)
 Insertion force : 10 N max
 Extraction force : 1 N min
 Durability : 10000 card insertions with 0.4µm Gold
 According to UTE C93-421

MATERIAL:
 Housing : PBT 30 % Glass Filled, Colour Black, Rated UL94V0
 Contacts and switch : Phosphor bronze
 Plating : Nickel all over with 3µm mini on contact area
 Gold on contact area : see catalogue part number key
 Tin/Lead 3 µm mini on soldertails
 FOR LEAD FREE PLATING :
 Matte Tin 3µm mini on solder tail in place of Tin/Lead
 Bare edge allowed

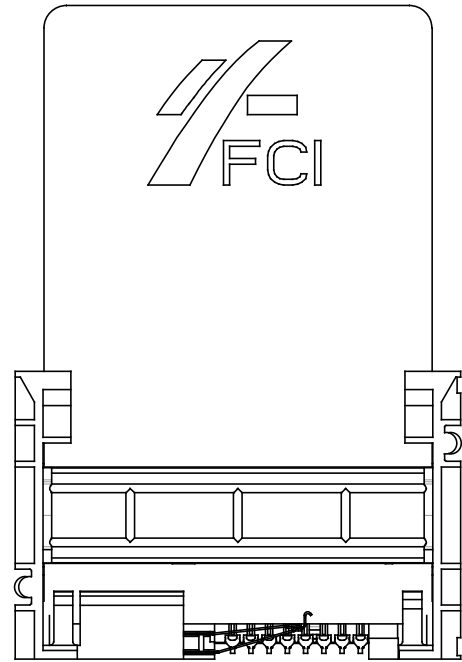
ENVIRONMENT:
 Operating temperature: -20°C / +70°C
 Storage temperature: -40°C / +85°C
 Printed Circuit Board thickness : 1.6mm

REFERENCE DOCUMENTS:
 Product specification VGN 11596
 Packaging Specification VGN 11619

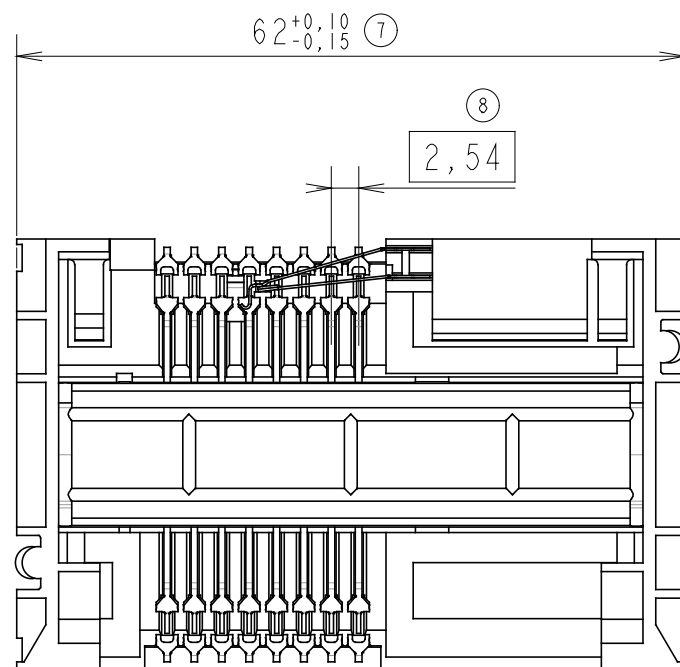
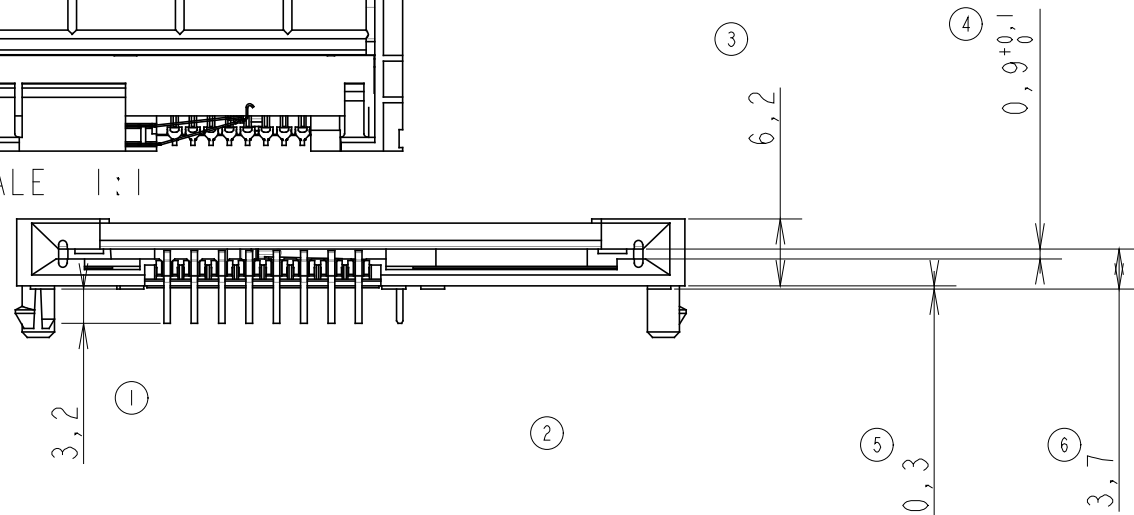
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SCALE 1:1



LEAD FREE VERSION:

"This product meets European Union Directives and other country regulations as described in GS-22-008"

The housing will withstand exposure to 260°C peak temperature for 10seconds in a wave solder application with a 1.6mm minimum thick circuit board. Use protective adhesive tape (Kapton or Teflon) or protective metallic devices on the areas which are directly exposed to wave soldering as it is used in classical leaded wave soldering

General Tolerances: ± 0.2 mm

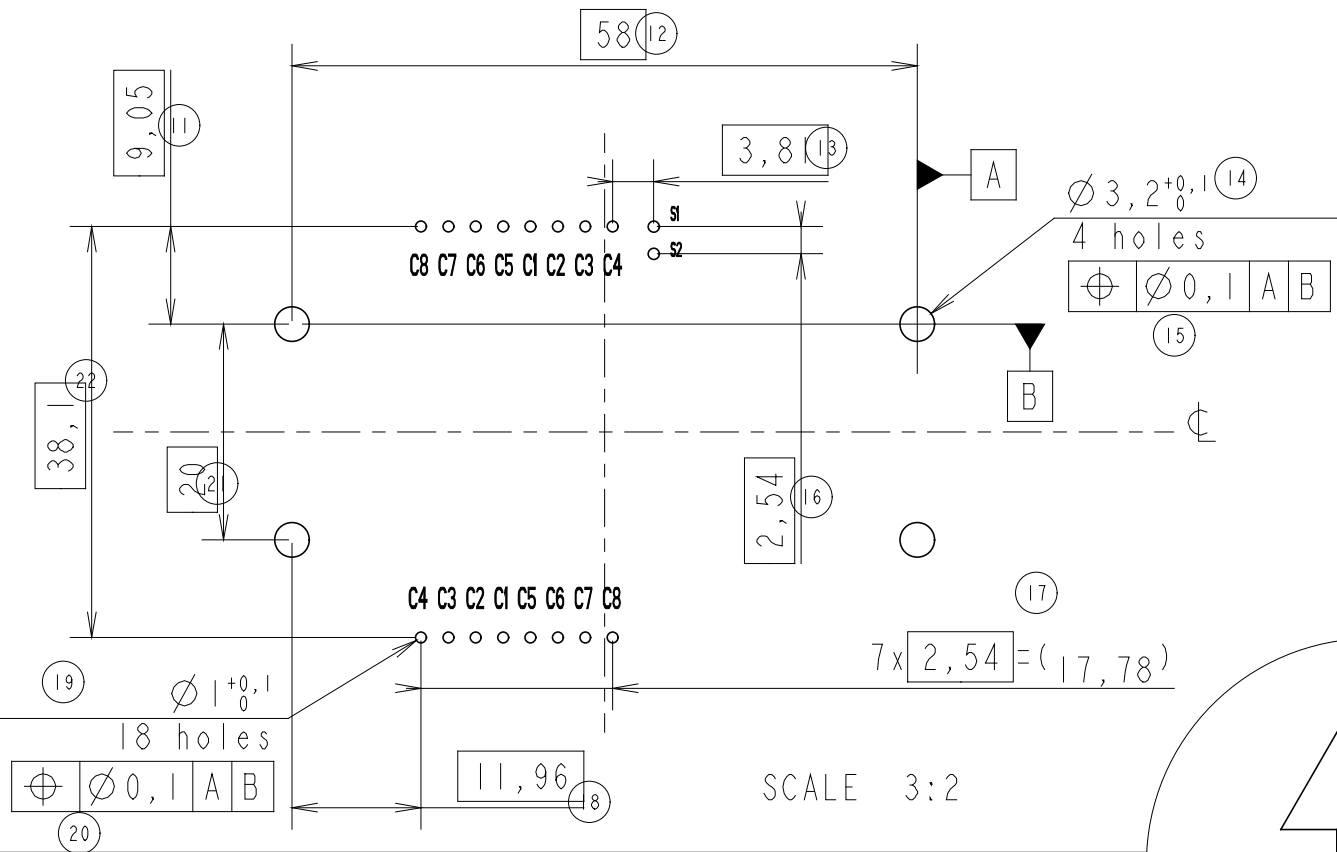
		www.fciconnect.com	surface - ✓ ISO 1302	tolerance ISO 406 ISO 1101	projection 	mm ↔
Dr	DILIPTHOMAS	02.04.30	Product family		5S2F	size
Eng	F TISSERAND	02.04.30	Spec ref		SEE NOTES	A3
Chr	N.TWENCY	'05/06/25	Material		SEE NOTES	ECN
Appr	K SOMA	'05/06/25				105-0071
title			L26 TYPE F01		dwg no	
					VJW_54701	
					Rev. C	
catalog no			SEE TABLE		CUSTOMER COPY	
					sheet 1 of 2	

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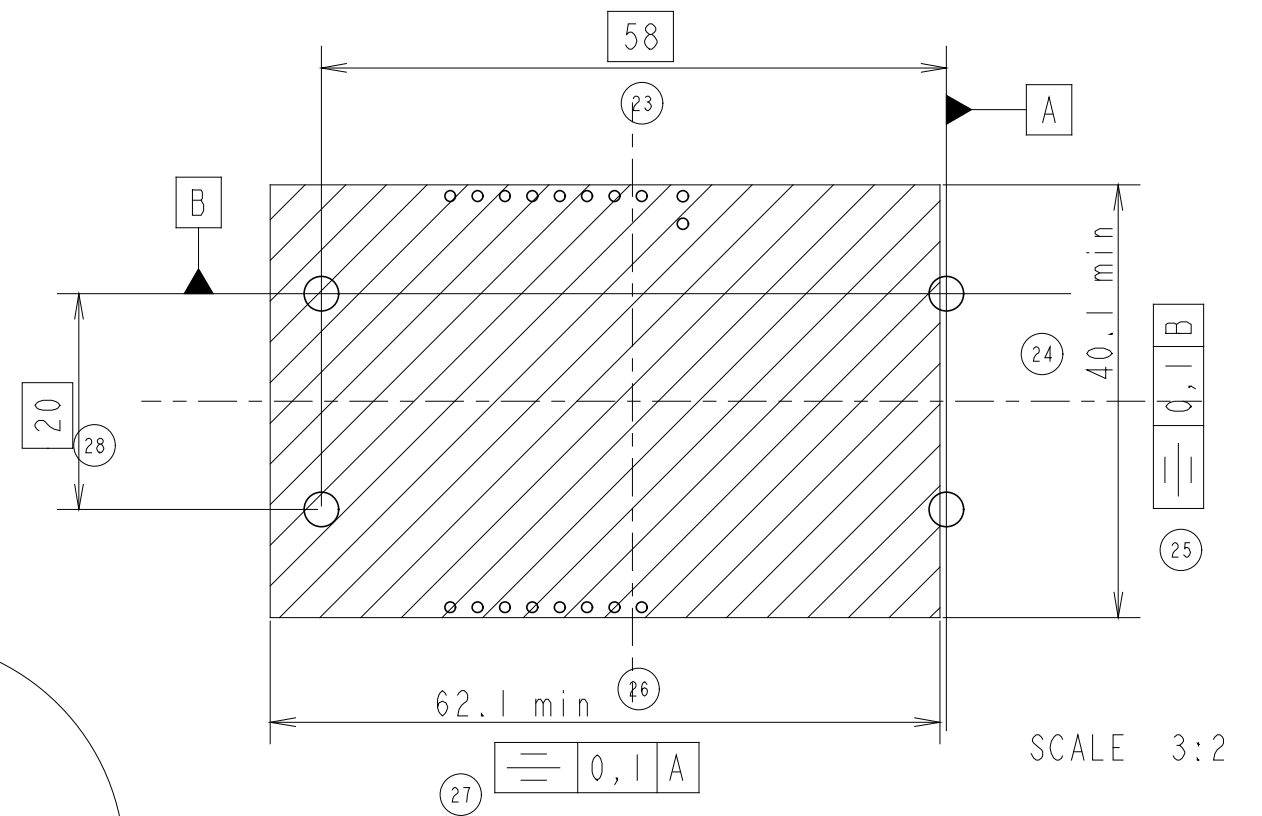


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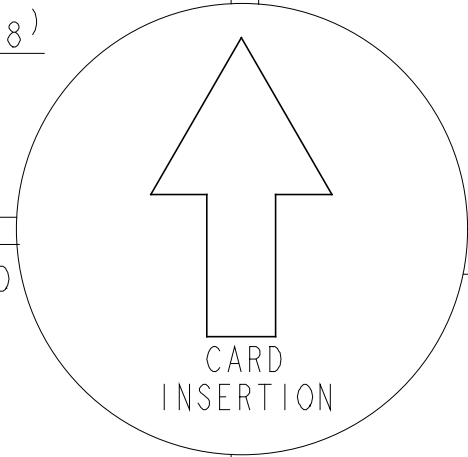
RECOMMENDED PCB LAYOUT CONTACT CONFIGURATION : ISO & AFNOR (CONNECTOR SIDE)



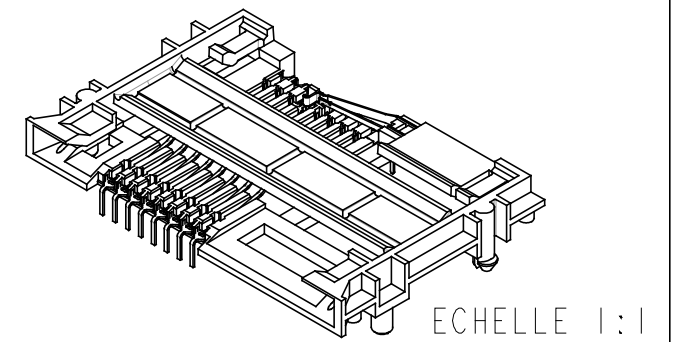
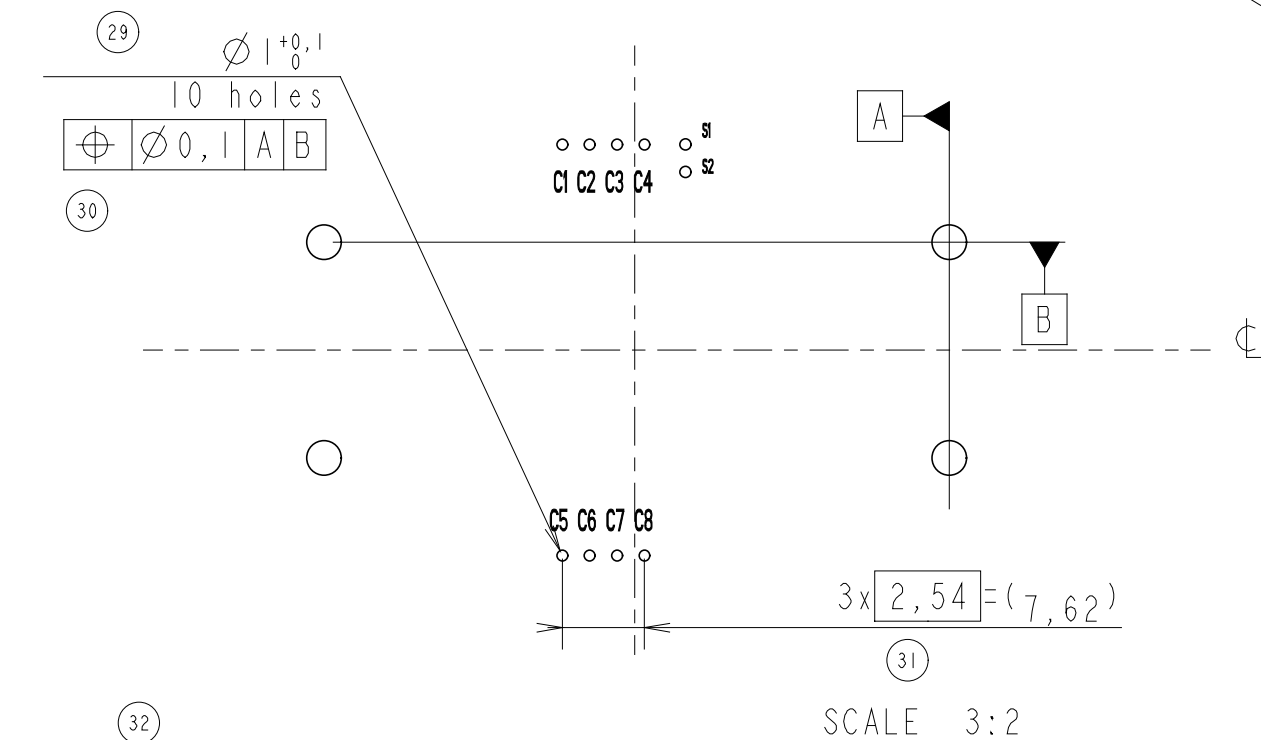
STANDARD LAYOUT FOR 'KEEP OUT ZONE' (Connector Side)



Hatching area might be free of components



RECOMMENDED PCB LAYOUT CONTACT CONFIGURATION : ISO (CONNECTOR SIDE)



EUROPEAN PROJECTION

		www.fciconnect.com	surface - <input checked="" type="checkbox"/> tolerance ISO 406 ISO 1101	projection	mm
Dr	DILIPTHOMAS	02.04.30	Product family	5S2F	size A3
Eng	F TISSERAND	02.04.30	Spec ref	SEE NOTES	Scale 3:2
Chr	N.TWENCY	'05/06/25	Material	SEE NOTES	ECN 105-0071
Appr	K SOMA	'05/06/25			
title L26 TYPE F01			dwg no VJW_54701		Rev. C
catalog no SEE TABLE			CUSTOMER COPY		sheet 2 of 2